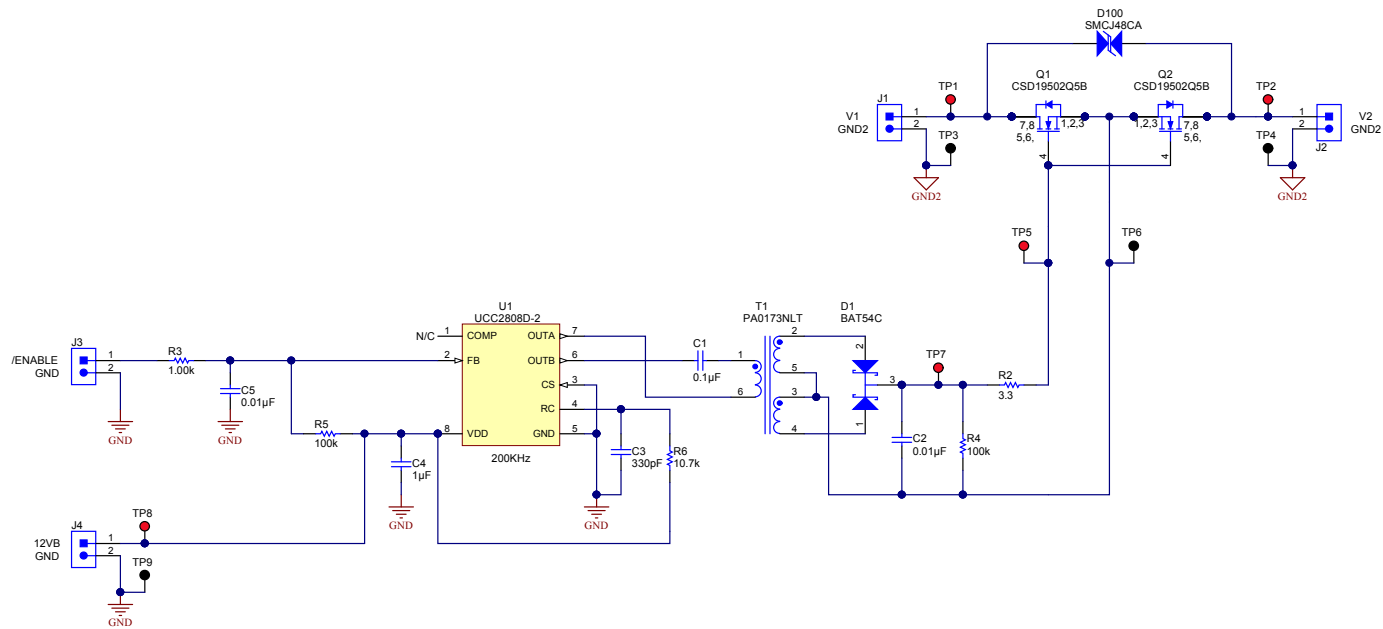


NOTES:
1) Mods required to PWB for REV.B.



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Number: PMP9522	Rev: B	Designed for: Public Release	Mod. Date: 4/2/2015
SVN Rev: Version control disabled	Assembly Variant: 001	Project Title: Solid State Relay	
Drawn By:	File: PMP9522 REV.B Sch.Doc	Sheet Title:	Sheet: 1 of 1
Engineer: J Betten	Contact: http://www.ti.com/support		Size: B

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